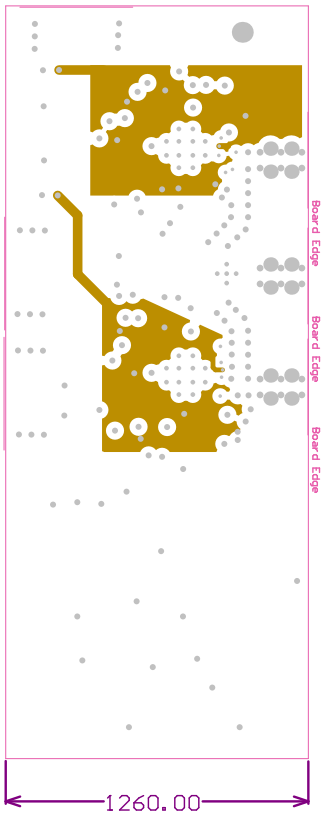
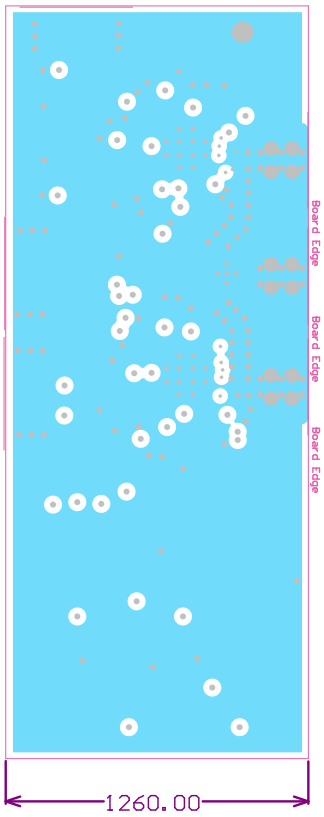


M2p Board Dimensions



M2 Board Dimensions



M2 Board Dimensions

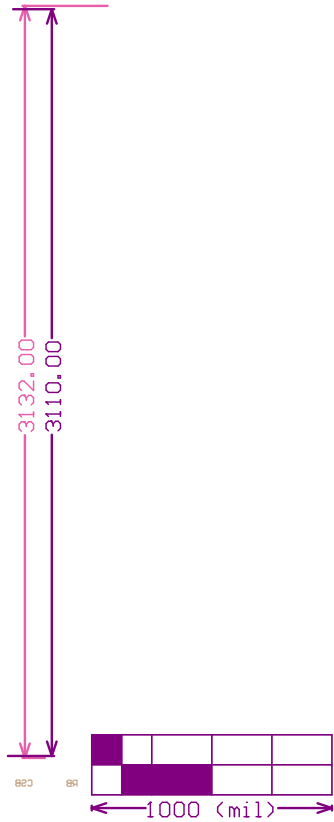
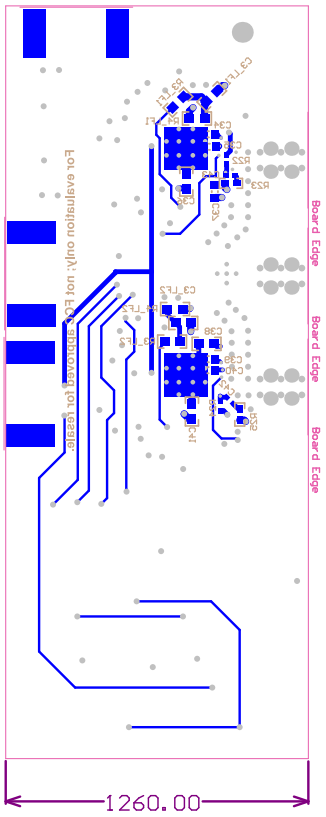
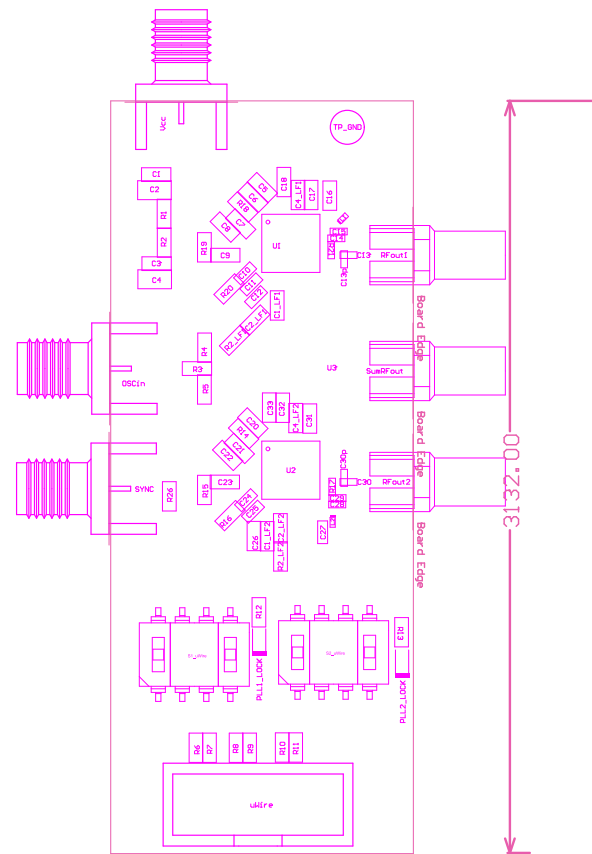


Fig 2. Board Dimensions



COMPONENTS PARKED 'DNP' SHOULD NOT BE POPULATED.

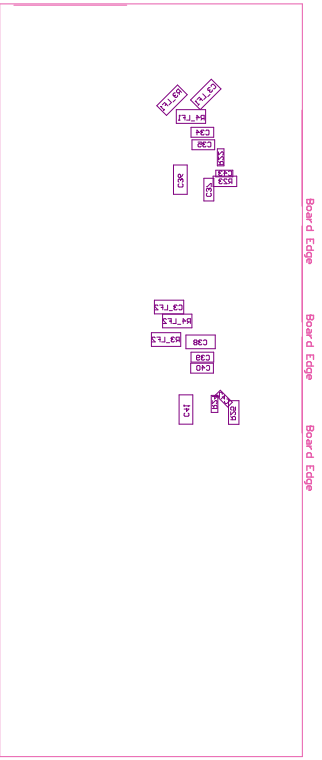
ASSEMBLY VARIANT

{No Variations}

PCB VIEWED FROM TOP SIDE	BOARD #:	TIDA-01346	REV:	A	SUN REV:	Not In VersionControl
M1 Board Outline		TID #:	.TID			
PLOT NAME =	Top Assembly Diagram	GENERATED:	4/6/2017	4:29:54 PM	TEXAS INSTRUMENTS	

PCB NEED FROM BOTTOM EDGE ASSEMBLY VARIANTS THIS VERSION	BOARD # 1010-A01346	REV A	2MM BREV Not In Use/Control
M1 Board Outline			
PART NAME = Bottom Assembly 01346.mw	GENERATED : 11/25/2024 4:28:00 PM	TERMS INGREDIENTS	

COMPONENTS MARKED "DPA" SHOULD NOT BE REPLACED.



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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